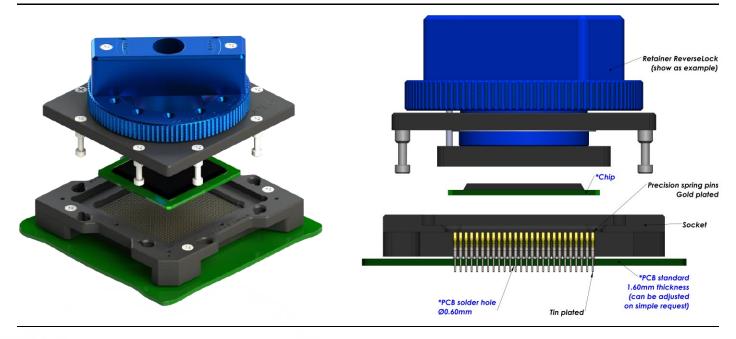
Through-hole (THT) soldering Test Socket

For LGA / QFN / MLF / MLP / LCC Package

1.27 mm pitch (from 1.27 mm upwards)





E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1270			
Application	Through-hole technology	Force	25 gr
Mounting	THT	Current rating	2.2 A
Bandwidth (GHz@-1dB)	3 GHz	Capacitance pF	< 1 pF
Contact resistance	<100mOhm	Inductance nH	< 2 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

How to order

Shape of tip Nbr of **Contact type** Option code (see page 16-19) **Plating** contacts P: Pointed 70: Standard THT D: Dead bug 95: Tin / Gold Depends on M: Multi frames Options: 72: Special THT to plug into MGS adapters 55: Gold/ Gold ballcount of chip U: Multi packages C: Crown Other on request C: Converter plate S: Custom opening slot L: Locating pegs Retention frame type (Lid) (see page 12-15) Grid code / A: Alignment plate Config. code H: Heatsink W: TwistLock S: ScrewLock F: Fan + Heatsink Will be given by the F:FastLock Q: Open QuickLock (<200 contacts) factory after receipt P: Thermal drain pad B:SpringLock of the chip datasheet D: QuickLock (>200 contacts) W: Transparent lid I: Steel retention lid H: Open Clamshell Alu (<200 contacts) M: Injection Molded ClamShell B: Aluminium retention lid J: Clamshell Alu (>200 contacts) R: ReverseLock T: Torque tool fixture L: Open Lever Clamshell Alu (>200 contacts) T: SlimLock G: Handling button

